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Table of Contents

Quantum multiscale modeling of transient material properties under femtosecond laser nonlinear irradiation	1
Zheng Xie, Cong Wang, Zhi Luo, Lan Jiang and Ji'An Duan	
Thermal Characteristics Simulation of Semiconductor Lasers Packaging for High Speed Application	8
Microstructure and viscoelastic behaviors of graphene/PMMA nanocomposites	12
Study on Enhanced Plastic Ball Grid Array (EPBGA) Package with Heat Spreader of Copper Plane	15
Lifetime evaluation on mid-infrared solid state laser	19
The Design of Image Rejection Mixer in W-band Jianping Gong, Mengya Lei, Yuzhu Wang and Yawei Li	22
Improving the Thermal and Mechanical Properties of Silicon Resin with Functionalized Graphene for Electronic Packaging	25
Preparation and thermo-mechanical properties of functionalized graphene/silicon rubber nanocomposites	30
Preparation of Graphene Aerogel and Its Electrochemical Properties as the Electrode Materials for Supercapacitors	35
Effect of AgNPs/Reduced Graphene Oxide Nanocomposites on the Electrical Performance of Electrically Conductive Adhesives	39
Explore of flexible package base on 3D printing technology	43
Sol-gel synthesis of Li2MnSiO4/C nanocomposite with improved electrochemical performance for lithium-ion batteries	46
Automated mechanical simulation system for microelectronic packaging	51

Surface Characterization and Electrical Properties of Spin-Coated Graphene Conductive Film	56
Weijun Zhang, Liming Gao, Xiaolei Ban and Ming Li	
Typical Failure Mechanisms and Precautions of the Plastic Optocouplers	60
Simulation analysis for a new low-cost wafer bumping technology	64
Electrochemical behavior of Sn-xZn lead-free solders in aerated NaCl solution	68
Package on Package SMT rework technology	74
Effects of 33um Bare Cu Wires' Mechanical Properties on Ball Bond Profile Fei Zong	79
Micro Heatpipe Integrated with LED Silicon Substrate	85
Design and Fabrication of Suspended high Q MIM Capacitors by Wafer Level Packaging Technology	89
Numerical Modeling of the Influence of Temperature and Driving Current on "Smile" in High Power Diode Laser Arrays	95
Increasing the bonding strength of chips and flex substrates assembly with a non-conductive paste by argon surface activation	.02
Study on Bond Pad Damage Issue in 33um Cu Wire Bonding on SMOS8MV Wafer Technology	.08
Leadframes' AuAg Plating thickness Influences to Stitch Bonding of Palladium Coated Copper Wires	.14
A Temperature-Controlled System for Loss Measurement of Transformer used in Switched-mode Power Supply	.18
Imitation chip design based on TSV 2.5D package	.22
Effective Thermal Conductivity Model for TSVs with Insulation Layer as Contact Resistance	.25
A Wet Process To Form Silica Thin Layer For Through Silicon Via Application	.32

A Study of Strain Gage Test during PCB Assembly Process	136
Effects of ZrO2 nanoparticles on the mechanical properties of Sn42Bi58 solder joint $Ze\ Zhu,\ Yan\ Cheong\ Chan\ and\ Feng\ Shun\ Wu$	140
Analysis on Thermo-Mechanical Reliability of TSV Interposer and Solder Joint	144
Molecular modeling design of polyaniline as carbon dioxide sensor	148
Influence of Electroplating Current Density on Through Silicon Via Filling Ying Zhu, Wei Luo, Zhipeng Chen, Ming Li and Liming Gao	153
Temporary bonding/debonding based on Propylene carbonate	158
Assembly process development of 2.5D integration for high performance processer Haiyan Liu, Feng Jiang and Kai Xue	161
Spot Welding Process Research of Fine Pitch Micro-Rectangular Connectors based on PU Enameled Wire	164
Optimal design of VFBGA mixed solder joints under random vibration	168
Potential-dependence of additives distribution in copper electrodeposition via filling Zhipeng Chen, Wei Luo, Ying Zhu, Ming Li and Liming Gao	172
Effect of Fiber Orientation in Glass Filled Plastic Enclosure on the Performance of Wire Bonds in Automotive Electronic Product under Thermal Cycling Environment	177
Advance Semiconductor Package Applied on High Efficiency DC-DC Buck Converter Cheng Yu Ho and Chen Chao Wang	183
Creep behavior of Cu/Sn-3.0Ag-0.5Cu/Cu solder joints under tensile stress coupled with DC current stressing	187
In situ aging study on the variation of Sn0.7Cu/Cu solid interface marked by bubbles Ma Haoran, Kunwar Anil, Sun Junhao, Zhao Ning, Huang Mingliang and Ma Haitao	193
Reliability of Pb-free solder joints in FCBGA using finite element simulation and Taguchi method	197
Effect of packaging asymmetry on the performance of a 2D MEMS thermal wind sensor with different heating geometries	201
Thermal Stress Analysis of Mesoporous Perovskite Solar Cell by Finite Element Method Ying Zhou, Hao Jiang, Guoping Wang, Peng Chen, Shannan Zhan and Sheng Liu	205

Preparation of Porous Au Electrode Used for Additives Investigation in Copper Filling 2: Xiu Mo, Ming Li and Junhong Zhang	:10
Fast single mode microwave-assisted synthesis of porous carbon xerogels for high performance supercapacitors	14
Xueqing Cai, Dayong Gui, Jianhong Liu, Guiming Tan, Wei Chen and Weijian Xiong	
SMT Product Character Recognition Based on Principal Component Analysis	18
Insights into the role of surface hydroxyl of the silica fillers in the bulk properties of resulting underfill	21
Stress analysis and structure optimization of copper cylinders based on 3D packaging 2: Wei Jiang and Lifeng Wang	26
The Finite Element Simulation and Nanoindentation Methods for the Study of Mechanical Behavior of Lead-free Solder Joints	231
The numerical investigation on mechanical behavior of BGA packages under board-level by using shear cycling loading	35
Electroless plating alloy thin-film embedded resistor materials	40
Strength Correlation of Power Chips by Finite Element Method	44
Effects of Soldering Temperature and Cooling Rate on the as-Soldered Microstructures of Intermetallic Compounds in Sn-0.7Cu/Cu Joint	:49
Electrochemically exfoliated graphene for applications in thermal and electrical conductions	:53
Effect of electromigration of Sn-xAg-Cu solder joints on its microstructure and mechanical properties	56
Morphological evolution and migration behavior of the microvoid in Sn/Cu interconnects under electrical field studied by phase-field simulation	:60
Grid-connected PV inverter reliability considerations: a review	66

	cch on resistance of electromigration of different connection form	275
	thesis of Elliptical Cu-Ag Nanoplates for Electrically Conductive Adhesives2 ng, Pengli Zhu, Gang Li, Baotan Zhang, Rong Sun and Chingping Wong	279
in printed		283
One-pot s	Hu, Pengli Zhu, Tao Zhao, Xianwen Liang, Rong Sun and Ching-Ping Wong withesis of silica nanospheres with bimodal size distribution for application in composite	288
	uo, Pengli Zhu, Gang Li, Tao Zhao, Daoqiang Lu, Rong Sun and Chingping	,00
Xie Jin	conductive adhesives based on silver coated copper flake fillers	294
0	Single Thin Film Resistor Network as 20dB Attenuator for DC-20GHz	007
	eg, Zewen Liu and Xiaotong Liang	191
Kirkendal soldering s	l crystal simulation of morphological evolution and growth kinetics of voids at the interface and in the intermetallic compound layer of Sn/Cu system under cyclic loading	301
Sn-ball/Sr	reactions and formation of intermetallic compound of a-3.0Ag-0.5Cu-paste/Cu joints in flip-chip on BGA packaging	307
	Response of A Molded Leaded Package in Wire Bonding Assembly Process	312
	l response of copper nanowires under torsion	318
corrosion	of metal-oxide/salt content in the aluminum soldering flux on solderability and resistance of Sn-0.7Cu/6061Al joints	323
Sn-0.45Ag	naracteristics and liquid–solid state reaction of Co–P films for low silver ;–0.68Cu–Ni–P solder	328
interface S	itu study of morphological evolution of the interfacial IMC in single-sided n-0.3Ag-0.7Cu/Cu joints during multiple reflow process	333
·	Application of Strain Measuring Technology in PCBA Reliability Evaluation 3 o, Qin Wang and Daojun Luo	338

The Effects of Rolling Deformation on Al-27%Si Alloys Prepared by Powder Metallurgy for Electronic Packaging Applications
Effect of SiCp particle size and anneal on properties of Al/SiCp composites prepared by powder liquid -phase sintering
W2W Wafer Level Vacuum Packaging for MEMS Devices Using Solder
A Wavelet Analysis on Digital Microstructure in Microbumps
Achieving High Reliability Via Pressureless Sintering of Nano-Ag Paste For Die Attach 367 Ning-Cheng Lee, Sihai Chen and Guangyu Fan
Study on microstructure, texture and thermal properties of LPSO reinforced Mg-Zn-Y(-Gd) alloys
Facile Synthesis of Silver Nanoparticles Decorated Boron Nitride Nanosheets Hybrids381 Fangfang Wang, Xiaoliang Zeng, Yimin Yao, Rong Sun and Jianbin Xu
The Risk and Solution for No-Clean Flux not Fully Dried under Component Terminations 387 Fen Chen and Ning-Cheng Lee
Status and Trend of SiC Power Semiconductor Packaging
Non-continuous IMC in Copper Wirebonding: Key Factor Affecting the Reliability 403 Allen Descartin, Meijiang Song, Beiyue Yan and Jun Li
Influence of Argon Reflow on the Microstructure and Properties of Lead-free Solder Joints 408 Yeqing Tao, Jason Guo, Dongyan Ding, Ting Li and Yunhong Yu
Prognostic Approaches for the Wirebond Failure Prediction in Power Semiconductors: A Case Study Using DPAK Package
High-performance supercapacitor Based on Metal Oxide Coated Fibrous Structure419 Chao Xu and Cheng Yang
Improving thermal management in high power LEDs through fabricating nano-twinned copper substrates
System design for anti-interference of smoke in metal liquid level detecting
Improvement in optical performance of white light-emitting diodes using randomly textured phosphor-in-glass
The Failure Mechanism of WLCSP Interconnect Under Board Level Bending Stress 436 Jeffrey Changbing Lee and Cheng-Chih Chen

Donghua Yang, Guoshuai Yang, Jian Cai, Qian Wang, Jingwei Li, Yang Hu and Liangliang Li	
he influence of the solider layer thickness on the interfacial reaction in the Ni/Sn/Cu	
zstem	. 44′
imulation and Experiment Study on the Jetting Dispensing Process Driven by Iechanical Collision	. 450
Peng Du, Guiling Deng, Can Zhou and Tao Wu	
the study on thermal crowding in high-power white light-emitting diode devices on uminaires	. 45
Zhenkun Sun, Jinxiong Chen, Lu Li, Dongdong Teng, Lilin Liu and Gang Wang	
tudy on the Surface Metallization in 3D Flexible Stack Package	. 45
ilver Dendrite-based Nanocomposites for Current Cutting-off Fuse	46
ffect of CeO2 Particles on the Low Phosphorus Electroless Ni Layer	46
ffect of CeO2 Particles on the Medium Phosphorus Electroless Ni Layer	47
ffect of CeO2 Particles on the High Phosphorus Electroless Ni Layer	. 47
he analysis of heat pipe cooling in high power LED lighting system	. 48
ilicon Carbide Power Electronic Module Packaging	. 48
nvestigation of Rheology Behavior of Lead-free Solder Paste	. 48
he study of Sn-0.3Ag-0.7Cu and Sn-1.0Ag-0.5Cu solder joint reliability under board	
vel drop impact	. 49
esign and properties of Sn-Bi-In low-temperature solders	49
xperimentally Validated Analysis and Parametric Optimization of Mechanical Shock esting of Advanced BGA Packages	50
he research of lead-free dispensing solder paste	50

Development of Fine Line Build-up Organic Substrate using Thin Film RDL Technology . 51 Xinyu Wang, Jian Cai, Yu Chen, Cheng Li, Xi He and Shuidi Wang	.3
Influence of Au film thickness on surface morphology and properties of substrate with	
Ni/Au microcones	.8
	กก
iNEMI Project on Automotive Electronic Material Challenges	12
A silicon-aluminum micro heat sink for light emitting diode (LED) chips	26
Investigation of Thermal Characteristics of a Silicon-Based LED Packaging Module 53 Mohammed Hamidnia, Liangliang Zou, Yi Luo and Xiaodong Wang	60
An easy realized ultra-narrowband filter	4
Failure Analysis on Bad Wetting of ENIG Surface Finish Pads	8
A new type of microstrip low-pass filter	12
A Novel Ultra-Wideband Filter With Wider Stopband Employing Multiple-Mode Resonator And Low-Pass Filter	6
Chaowei Song, Sha Li, Yuzhu Wang and Xu Wang	
Stretchable Copper Wires based on Reduction of Active Metallic Nanoparticles and Electroplating	0
Implementation of Non-linear Viscoelasticity for Epoxy Based Thermoset Polymers 55 Hong Yan, Przemyslaw Gromala and Papathanassiou Dorothea	55
The hybrid method is introduced to use in suppression to synchronous switch noise 56 Liuping Wang, Dongkai Shangguan and Liqiang Cao	5 1
Ultrasonic-assisted soldering of Sn-based alloys during die bonding for high-temperature application	i4
The interfacial thermo-mechanical reliability of 3D memory-chip stacking with through silicon via array	i8
Hui-Hui Yuwen, Min-Bo Zhou, Xin-Ping Zhang and Hong-Bo Qin	
Graphene-Ag Composite Film as Thermal Interface Materials	4
The effect of flux components on the slump-in-heating resistance of Sn-3.0Ag-0.5Cu	
solder paste	6

A.C. A.D. LA DIA WILD LIM LD C C CA D. L. FOR
A Compact Band-stop Filter with Wide Bandwidth and Far Spurious Stop Bands 585 Yuzhu Wang, Xi Tian, Jianping Gong, Xueling Jing and Tianyiyi He
Copper Pumping of Through Silicon Vias in Reliability Test
Thermal Placement Optimization for Embedded Resistances Based on Orthogonal Design and Fuzzy Genetic Algorithm
Study on impacts of configuration parameters on flip stacked Au bumps stress and strain under random vibration load
3D Multiphysics Modelling of High Voltage IGBT Module Packaging
Monitoring the Stress Evolution of Through Silicon Vias during Thermal Cycling with Infrared Photoelasticity
Flip Chip Technology and Its Application in Microwave Module
Thermal Performance and Reliability Management for Novel Power Electronic Packaging using Integrated Base Plate
Influence of Properties and Microstructures on Thermal Fatigue Testing of a High-power LED
Jibing Chen, Nong Wan, Juying Li, Zhangwen He, Yanfang Yin and Yiping Wu
Development of TSV-based Inductors in Power Electronics Packaging
Investigation of thermal-mechanical stress and chip-packaging-interaction issues in low-k chips
Radiation analysis of embedded capacitors based on HFSS
Investigation of PoP package structure with copper pillar replace the solder ball
Comparison of thermal characteristics of Light-emitting Diode chips and electrical heating source
Ink-jet printed high conductive silver traces on polymer substrates sintered at room temperature by a camera flash lamp

Ultra-Thin Chip on Flex by Solder-on-pad (SoP) Technology	45
Size and geometry effects on the electromigration behavior of flip-chip solder joints 68 Hong-Bo Qin, Wu Yue, Dao-Guo Yang and Xin-Ping Zhang	51
A Failure Analysis on Leakage of Ceramic Capacitor	56
Research on the microstructure and shearing property of microbumps with one Sn grain for high density solder interconnects	59
Optimization for solder layer thermal characteristics of the power transistor based on structure function	62
Classification and 3D Stack of Embedded Components Technology in Substrate	66
Improvement of DRIE simulation method for process development application 6' Hong Du, Min Yu, Baohua Shi, Zhao Zhang, Hao Wang, Yufeng Jin, Lin Qi, Zhiyuan Zhu and Haixia Zhang	72
Electroplating Cu on ALD TiN for high aspect ration TSV	76
Study on Rework Process of BGA Components	81
The numerical investigation on the stiffness of CuCGA interconnection under the condition of shearing	85
Stress analysis and parametric studies for the ultralow-k chip in the flip chip process 68 Lin Lin, Jun Wang, Lei Wang and Wenqi Zhang	89
Analysis of measurement accuracy of air flow sensor influenced by moisture	94
Fabrication of Microchannel Embedded TSV Interposer and its Influence on TSV's Electrical Parameters	99
Study on the impact of height of solder joint with compliant layer on stress and strain under thermal cycle	05
The effect of stress on the mean time to failure (MTTF) of solder under electromigration . 7 $Xiaoxu\ Pan,\ Fei\ Su\ and\ Tianbao\ Lan$	11
Clarification of Cu rich phase in SAC/FeNi solder joints	15

Design, Fabrication and Stress Evaluation of Low Stress Si Electrical Interconnection Air-gapped from Si Interposer
Shenglin Ma, Yanming Xia, Rongfeng Luo, Fei Su, Kuili Ren, Jing Chen and Yufeng Jin
The reliability of through silicon via under thermal cycling
Study on the failure behavior of BGA solder interconnections under fatigue loading 729 Xing Xu and Gaiqing Chen
The effect of electric current and the external load on the growth of tin whiskers
Effects of magnetic field on reliability issues of lead-free solder joint
Study on the Oil-filled Isolated Pressure Sensor by a Fluid-solid Coupling Method
Creep behaviors of Pb-Free Solder Joints during Current Stressing
A Rectangular Coaxial Line Low-Pass Filter With Simple Structure
Gradient refractive index encapsulant layer for enhancing light extraction efficiency of multi-chip LED packaging
Effect of Viscoelasticity of PDMS on Transfer Printing
Failure modes in GZO FC-light-emitting diodes
Development of Structure Function Analysis System for Power Semiconductor Devices770 Xiufu Que, Yanan Liu, Lianqiao Yang, Wei Chen and Jianhua Zhang
Quality Evaluation and Simulation of Through-Multilayer TSV Integration Process for Memory Stacking
Electrochemical Analysis of the Effect of Accelerator in Methanesulfonic Acid Bath for Copper Electrodeposition
Reliability of TSV interconnects: thermal shock and mechanical properties
Effects of Cu Orientation on the Microstructure of Sn-2Ag-2.5Zn /Cu Interface 789 Penghui Xu, Fengtian Hu, Anmin Hu and Ming Li
Test procedure of indoor lighting LED luminaires based on step-stress accelerated degradation test

A broadband 3dB orthogonal bridge in w-band
Electrical Simulation of A Shielding Structure in 3D Package
Optimization of a zoom mechanism with flexible hinge for dispenser valve
The thermal mechanical reliability of TSV during the fabrication process
The Realization of Big Networking Dream from Challenging Electronic to Interconnect Process Technology (Part 1)
Study on Au-Ag Bond Technology 3D Stacked Package
The energy release rate of the micro-cracks in the ultralow-k chip during the flip chip process
Investigation of the Influence of Ag Reflective Layer on the Correlated Color Temperature and the Angular Color Uniformity of LED with Conformal Phosphor Coating
Bond reliability under humid environment for Pd coated Cu and Ag alloy wire bonding835 Yahong Du, Tao Xiong, Zhibo Yuan, Fei Leng, Hailan Lv, Zhiquan Liu and Daquan Yu
Preparation and characterization of a two-component silicone gel sealant
A Novel Bump-CPW-bump Structure for Interconnection/Transition of RF MEMS Packaging
A new copper ink with low sintering temperature for flexible substrates
Reliability of Graphene-based Films Used for High Power Electronics Packaging 852 Shirong Huang, Yong Zhang, Nan Wang, Ning Wang, Yifeng Fu, Lilei Ye and Johan Liu
Printed-circuit board Model Establishment and Solder joint Failure Analysis 856 Yuming Wang, Youwang Cao and Shengyu Zhang
A review about the filling of TSV
Dielectric properties of CVD graphene/BaTiO3 /polyvinylidene fluoride nanocomposites fabricated through powder metallurgy

Fracture Strength of Silicon Wafer after Different Wafer Treatment Methods
Effect of Electroplating Parameter on the TSV-Cu Protrusion during Annealing and Thermal Cycling
Triple band-notched UWB antenna with tapered microstrip feed line and slot coupling for bandwidth enhancement
Enhancing Angular Color Uniformity of White Light-Emitting Diodes by Cone-Type Phosphor Layer Geometry
The Characterization of TSV Cu Protrusion under Thermal Cycling
Residual Stress Measurement of the Ground Wafer by Stepwise Corrosion and Raman Spectroscopy
Sun Jinglong, Qin Fei, Ren Chao, Chen Pei, Yu Huiping, Wang Zhongkang and Tang Liang
Optical performance enhancement for remote-type Light-Emitting Diodes with quantum dots-polymer film through a new packaging structure
Numerical and experimental study of lens manufacturing based on electrohydrodynamics for light-emitting diodes
Substrate Design of a 3-D Microwave Front-end Multi-Chip Module with Antennas Integrated
Degradation mechanisms of solder joints on printed circuit boards during storage determined by infrared multi-point temperature measurements
Reliability study of power electronic packages by using an irreversible cohesive zone model 915 Lingling Zhu, Yangjian Xu, Jicheng Zhang, Lihua Liang and Yong Liu
The effect of micro-structure evolution in electromigration on the reliability of solder joints 921 Jicheng Zhang, Lihua Liang, Yangjian Xu and Yong Liu
De-embedding Transmission Line of SiO2 Thin-film Measurements for Accurate Characteristics
Essential factors influencing the wettability of Sn-3.0Ag-0.5Cu solder balls on Au substrate of the right-angle solder interconnect in laser jet solder ball bonding

The Modeling of DC Current Crowding for Through-silicon Via based in 3-D IC
System integration of a SERF atomic magnetometer on a glass wafer substrate 939 $Yu\ Ji,\ Jintang\ Shang,\ Lei\ Wu\ and\ Qi\ Gan$
Fabrication of wafer-level micro silicon heaters for chip scale atomic magnetometers \dots 943 $Lei~Wu,~Qi~Gan,~Yu~Ji~and~Jintang~Shang$
Wafer-level optical packaging for chip-scale atomic magnetometers
Hemispherical Wineglass Shells Fabricated By a Chemical Foaming Process 951 $Bin\ Luo\ and\ Jintang\ Shang$
Parasitic Parameter Extraction and Modeling of Via of High Speed Differential Pairs 955 $\it He~Huimin$
Effect of Microstructure and IMC on Single SnAgCu Solder Joint by Rapid Thermal Cycles
Ab Initio Studies of the Differences in the Chemical Reactivity and Electronic Properties of Polyaniline and its Derivatives
Opening the Hole of the Backside Silicon and Forming the Alloy Bump For TSV
A method for radiated emission test of the IC module
Simulation of Copper Electroplating Fill Process with Different Parameters for Through Silicon Vias
Degradation of the Die Attach Layer in Chip-on-Board Packaged Light-Emitting Diodes during Temperature Cycling
High concentration Ag nano-particles ink preparation and related writing system for paper-based writing electronics
Gas Adsorption on Graphene with Different Layers: A First-principles Study
The development of 3D aerospace SRAM integration technology using silicon Interposer 994 He Xin, Shan Guang-Bao and Du Xin-Rong
Effects of heatsink on the performance of high power semiconductor lasers

Lifetest system for assessing reliability of high-power semiconductor laser diodes 1001 Wenbin Liu, Taishan Wang, Chengpeng Li, Hong Xia, Martin Hai Hu and Yan Liu
Research on Smart Sensing RFID Tags under Flexible Substrates in Printed Electronics 1006 Shihui Zhang, Song Li, Jian Ma, Shuo Chen and Hongyuan Chang
Preparation and Characterization of solution-processed MWCNT-Ag matrix composite films
Effect of 0.8wt% Al2O3 nanoparticles addition on the microstructures and electromigration behavior of Sn-Ag-Cu solder joint
Failure Mode Analysis for the Solder Joints for the Flip-chip Light Emitting Diodes 1018 Yang Liu, Fenglian Sun, Hao Zhang, Tong Xin and Guoqi Zhang
Design and analysis on SMT QFN silicone keypads
Research on low temperature bonding using nanoporous copper
Comparison of the break-up behaviors of newton and shear thinning non-newton fluid in jet dispensing for LED packaging
A Novel Heat Substrate with Self-alignment Structure for High-power LED Packaging 1033 Hao Cheng, Xuebin Zhang, Huai Zheng and Mingxiang Chen
Influence of rubber nanoparticles on the properties of Novolac-diazonaphthoquinone based photoresist
Embedding chip into substrates with cavities for high density packaging
Impact of the design parameters uncertainty on the PC-white LED color constancy based on the theory of the uncertainty
Improvement of Optical Performances of LEDs by Dual-layer Structure of nano-TiO2 and Phosphor
Nano-mechanical properties of Single Grain Sn micro-bumps
Spreading Behaviors of Silicone Droplet Impact on Flat Solid Surface: Experiments and VOF Simulations
Experimental Study of Chip Offset on the Packaging Consistency of High Power
Light-Emitting Diodes

Mengyu E	uang, Lan Li, Chao Yuan, Bin Xie, Xingjian Yu and Xiaobing Luo
	hly Accelerated Thermal Cycling Test for DC/DC Converter
	of liquid SnPb film on the gold-coated copper wetting channel
_	llimeter wave package based on multilayer ceramic technology
	package and applications of ultra-thin sensor chip
	deling and Optimization for Electronic Packages
	del of Phosphor Self-Heating in Phosphor-Converted Light-Emitting Diodes . Zhu, Jinyan Hu, Run Hu, Bin Duan and Xiaobing Luo
Light-emitti	l Substrate Structure for High Angular Color Uniformity of White ag diodes with Conventional Chips
	fusion characterization and comparison of different packaging materials Ma, Zhixue Liu and Qiulin Ding
	f Quasi-Hermetic Packaging solution for MEMS
	sign of through silicon via interconnects and growth of carbon nanotubes Xu and $Zheyao$ $Wang$
tests	rsis of solder interconnects under the electro-thermal-mechanical coupling
	mulation of heat transfer cooling down by water in microgap structure Shen, Zhihui Wen and Jinsong Zhang
_	Experimental study on droplet-on-demand jetting system for multi-materials $u,\ Dan\ Xie,\ Xuefeng\ Chang,\ Jian\ Wang,\ An\ Xie\ and\ Liang\ Yang$
Stressing	ze Effects on the Elements Consuming at the Solder Pad under Current g, Fenglian Sun, Xuemei Li, Yang Liu and Tong Xin
Conductive	Polymer Adhesive Electrodes Reinforced by Cheng Yang, Zhexu Zhang and Ruobing Zhang
Reliability A	nalysis of and Experiment Test on SAC305 Solder Balls

Reliability Analysis and Thermal Resistance Degradation of High Power Chip in the Harsh Environment
Wenchao Tian and Haoyue Ji
Study on High Thermal Conductivity and Thick-Thin Film Hybrid Technology of AlN Substrate
Analysis of a double-phase regulation and ultra wideband tunable micro electromechanical system resonator
Measurement of thin-film residual stress based on single-beam lever method
Study on Electrical Performance of Stacking Die Package with Silicon Interposer
Fabrication of a novel cantilever-based device by release the stress in a reliable way1162 Shuaipeng Wang, Jinling Yang, Yanning Chen, Haifeng Zhang and Dongyan Zhao
Effect of Magnetic Particles on the Microstructure and Wettability of Sn-Zn lead-free solders
Research on robustness of MEMS-based wearable sensors
An improvement of the membrane structure of MEMS piezoresistive pressure sensor1174 Zebang Huang and Xiaosong Ma
The optimization of process parameters based on the orthogonal experiments in wire bonding
Fall Detection Analysis with Wearable MEMS-based Sensors
On-line measurement and analysis of LED characters in accelerated life test
Optimization and analysis of micro capacitive comb accelerometer
A novel pin-pull tester and its application on PCB pad cratering assessment
Low Loss CCTO@Fe3O4/ epoxy Composites with Matched Permeability and Permittivity for High Frequency Applications
The indentation size effect on SnAgCu lead-free BGA solder joints at elevated temperatures
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Ultrahigh Power Graphene Based Supercapacitors
Microstructure and mechanical properties of Sn-Bi lead-free solder during extruding and drawing process
Numerical Analysis and Parameter Optimization of Thermal Stress Effect for Low-K Layer Flip-Chip with Copper Pillar Bump
Finite Element Analysis for the Wire Bonding Process and Impact Force Variation 1224 Yongjun Jiang, Tan Chongfeng, Gao Jian, Chen Yun and Chen Xin
Packaging process research of power MOSFET, against salt spray corrosion, in Aerospace electronic products
Design and fabrication of a silicon microvalve for large flow application
A novel numerical method of computing the stress intensity factors of the interfacial cracks 1238 $Xin\ Lan\ and\ Nao-Aki\ Noda$
Effect of Viscoelastic Behavior of EMC on Predicting QFN Fatigue Life
2D Finite Element Analysis of IGBT Solder Joints
Analysis of copper plating layer discoloration caused by petal-shaped clusters morphology 1252 Zheng Yuwei Yuwei and Bao Shengxiang
Analysis on the causes of decline of MLCC insulation resistance
A New Method of Robust Phosphor Glass Fabrication and Performances for LEDs 1258 Liang Yang, An Xie and Dan Xie
Interfacial reactions in Cu/Sn/Cu(Ni) systems during soldering under temperature gradient
Microstructure and Mechanical Properties of Al/Sn-Zn-Bi-Ni/Cu Solder Joints
Synchrotron radiation in situ study on liquid-solid thermomigration in Cu/Sn/Ni solder joint
Yi Zhong, Mingliang Huang, Haitao Ma and Ning Zhao Effect of Sn grain orientation on substrate dissolution and IMC formation in SnAgCu solder interconnect undergoing electromigration

Effect of Cu on Interfacial Reaction in High-lead Solder Bumps
Effects of Stirring Speed on Composition and Morphology of Non-cyanide Co-electroplating Au–Sn Thin Films
High Efficient and Color Rendering Quantum Dots Optimized White Light Emitting Diodes
A new method for reducing warpage due to reflow in IGBT module
Detection of Plated Through Hole Defects in Printed Circuit Board with X-ray
Wafer Level High Precision Small Size Inductors for RF Application
Silicon Based Wafer-level Packaging for Flip-chip LEDs
Study of Fine pitch Cu pillar solder flip chip interconnect on high density flexible substrate 1309 ${\it Pun~Kelvin}$
Low temperature hermetic packaging with Ag sintering process
The effects of Au film thickness on the reliability of Sn-Pb solder joints
Design and simulation of CCGA ALN ceramic package
Electrical Simulation of Gold Bonding Wire with Different Parameters
Research on the impact of heat treatment on coating quality and reliability of welding after plating nickel
A study on thermomechanical reliability of flip chip package based on MUF process 1338 Xiaotian Meng, Lin Tan, Qian Wang, Chuan Chen, Xionghu Wang and Jian Cai
Study on pick-up process of thin die based on Taguchi Method
Advanced plating photoresist for advanced IC packages
Lift-off photoresists for Advanced IC packaging metal paternning

Design of a new type micro-tri-mode filter
Electroless deposition of copper alloy in the PEG additive
Interfacial reaction and IMCs formation between Sn-0.7Cu solder and Cu substrate during reflow soldering
Effects of assembly process states on RF transmission properties in passive microstrip circuit
Yingxia Qiu, Zhixian Min, Jun Hu, Xuelin Peng and Congsi Wang
A new kind of circular polarized slotted waveguide array antenna
Performance analysis of pre-oxidation process direct bonding copper substrate
Intermittent operating life results for different control strategies
Complementary duplexer
Yawei Li, Chaowei Song and Yang Wang
A circularly polarized antenna based on EMSIW sub-array with high front-to-back ratio 1390 $Ya-Hua\ Ran,\ Yang\ Peng\ and\ Jiawei\ Li$
Design of an Ultra-wideband Monopole Antenna With Dual Band-Rejected Characteristic 1394 Ya -Hua Ran, Zhangjing Wang and Junwei Li
Waveguide Slotted Array Antenna for Circularly Polarized Radiation Field
Wide Stopband Ultra-Wideband Suspended Stripline Filter
A Design of Ka Band Detector
Estimation of Inter-Symbol Interference (ISI) using Clock Pattern
A Compact Printed Triple-Band Antenna for Wireless Applications
A Compact Frequency-Reconfigurable Antenna Empolying Novel Composite Right/Left-Handed Transmission-Line Structure
A Terahertz-band E-plane Waveguide Directional Coupler With Broad Bandwidth 1419 Huan Xin, Sha Li and Yang Wang

Flow Boiling Heat Transfer Characteristics of HFO-1234yf for Electronic Packaging Cooling with a Microchannel of Triangular Cross Section
A Symmetric Directional Coupler With Broad Band And Improved Directivit
A New Type of Microstrip Band-stop Filter Using Spurline
Optimization of Structure for BGA Packaging Based on Taguchi Method
Numerical simulation and thermal analysis of PoP packaging
Failure analysis for poor solderability of Au surface of PCB
Gradient refractive index glass films for LED packaging
Power QFN Device Bump ball Lift Issue Study
A Novel Dsign of UWB Microstrip High-pass Filter
Design of a novel suspended substrate stripline highpass filter
Reliability Analysis and Case Studies on FCBGA Packaged Devices
Study of MEMS gas sensor and its packaging
PSO based on chaotic Map and Its Application to PID Controller Self-tuning
Interfacial Microscopic Reaction Mechanism of Lead-free Attachment Material in IGBT
packaging
MEMS Gyro Sensor using Flexible substrate for Package Size Reduction
Thermal modeling and analysis for Ceramic Quad Flat No-lead packages
Simulation and Testing of Large-scale IC Ceramic Packages with Differential Routing1494 $Xiao$ -Jun Zhang, Qiang Duan, Ling Gao and Hang-Zhou Li
Effect of solder alloy composition on its solid-state bonding quality with Ni microcones 1497 Zhuo Chen, Hu He, Anmin Hu and Ming Li